### 501857528 03/19/2012

### PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

### **CONVEYING PARTY DATA**

Name	Execution Date
Chun-Wei HSU	12/29/2011
Jiun-Lei Jerry YU	01/03/2012
Fu-Wei YAO	12/29/2011
Chen-Ju YU	12/29/2011
Po-Chih CHEN	12/29/2011
King-Yuen WONG	12/29/2011

### **RECEIVING PARTY DATA**

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City:	Hsinchu
State/Country:	TAIWAN
Postal Code:	300

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13339052

### **CORRESPONDENCE DATA**

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**PATENT** 

REEL: 027885 FRAME: 0195

NAME OF SUBMITTER:	Randy A. Noranbrock
Total Attachments: 2 source=efiledassgn2012-03-19#page1.tif source=efiledassgn2012-03-19#page2.tif	

PATENT REEL: 027885 FRAME: 0196

## ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) Chun-Wei HSU

Chen-Ju YU 4)

Jiun-Lei Jerry YU 2)

5) Po-Chih CHEN

3) Fu-Wei YAO

King-Yuen WONG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

#### TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

### 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300 Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

### HIGH ELECTRON MOBILITY TRANSISTOR AND METHOD OF FORMING THE SAME

- for which an application for United States Letters Patent was filed on December 28, 2011, and identified by United States (a) Patent Application No. 13/339,052; or
- for which an application for United States Letters Patent was executed on \_\_\_\_\_ (b)

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

Chun Wei Hou

Name: Fu-Wei YAO

Fin-wei You

>9/12/2011 Date: 03/01/2012

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6) King-Yuen Wong

Date:  $\frac{29/12/201}{19/12/201}$ 

Date:

Date: 2 | | 2 | 20 | 1

PATENT REEL: 027885 FRAME: 0198

**RECORDED: 03/19/2012**